



PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Group Art Unit: 2826

Application No.: 09/856,924

Examiner: Tan N. Tran

Filed: May 30, 2001

Docket No.: 109681

For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME,
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed June 18, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1, 3, 7, 10 and 13 as follows:

B' Sub C' >

1. (Amended) A semiconductor device comprising:
a substrate including a plurality of holes and a surface over which an interconnecting pattern is formed, part of the interconnecting pattern being superposed over the holes;
a semiconductor chip disposed over another surface of the substrate and including a plurality of electrodes to be positioned over the holes; and
conductive posts provided on the electrodes and within the holes to be electrically connected to the interconnecting pattern.

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3. (Amended) The semiconductor device as defined in claim 2,
wherein the resin is an anisotropic conductive material containing conductive particles; and